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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-WFQFN Exposed Pad
Supplier Device Package	28-HWQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f211b3np-u0

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1. Overview

These MCUs are fabricated using the high-performance silicon gate CMOS process, embedding the R8C/Tiny Series CPU core, and is packaged in a 20-pin molded-plastic LSSOP, SDIP or a 28-pin plastic molded-HWQFN. It implements sophisticated instructions for a high level of instruction efficiency. With 1 Mbyte of address space, they are capable of executing instructions at high speed.

Furthermore, the R8C/1B Group has on-chip data flash ROM (1 KB × 2 blocks).

The difference between the R8C/1A Group and R8C/1B Group is only the presence or absence of data flash ROM. Their peripheral functions are the same.

1.1 Applications

Electric household appliances, office equipment, housing equipment (sensors, security systems), portable equipment, general industrial equipment, audio equipment, etc.

Table 1.2 Functions and Specifications for R8C/1B Group

Item		Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns ($f(XIN) = 20$ MHz, $VCC = 3.0$ to 5.5 V) 100 ns ($f(XIN) = 10$ MHz, $VCC = 2.7$ to 5.5 V)
	Operating mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	See Table 1.4 Product Information for R8C/1B Group
Peripheral Functions	Ports	I/O ports: 13 pins (including LED drive port) Input port: 3 pins
	LED drive ports	I/O ports: 4 pins
	Timers	Timer X: 8 bits \times 1 channel, timer Z: 8 bits \times 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits \times 1 channel (Input capture and output compare circuits)
	Serial interfaces	1 channel Clock synchronous serial I/O, UART 1 channel UART
	Clock synchronous serial interface	1 channel I ² C bus Interface ⁽¹⁾ Clock synchronous serial I/O with chip select (SSU)
	A/D converter	10-bit A/D converter: 1 circuit, 4 channels
	Watchdog timer	15 bits \times 1 channel (with prescaler) Reset start selectable, count source protection mode
	Interrupts	Internal: 11 sources, External: 4 sources, Software: 4 sources, Priority levels: 7 levels
	Clock generation circuits	2 circuits • Main clock generation circuit (with on-chip feedback resistor) • On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has a frequency adjustment function
	Oscillation stop detection function	Main clock oscillation stop detection function
	Voltage detection circuit	On-chip
	Power on reset circuit	On-chip
Electric Characteristics	Supply voltage	$VCC = 3.0$ to 5.5 V ($f(XIN) = 20$ MHz) $VCC = 2.7$ to 5.5 V ($f(XIN) = 10$ MHz)
	Current consumption	Typ. 9 mA ($VCC = 5.0$ V, $f(XIN) = 20$ MHz, A/D converter stopped) Typ. 5 mA ($VCC = 3.0$ V, $f(XIN) = 10$ MHz, A/D converter stopped) Typ. 35 μ A ($VCC = 3.0$ V, wait mode, peripheral clock off) Typ. 0.7 μ A ($VCC = 3.0$ V, stop mode)
Flash Memory	Programming and erasure voltage	$VCC = 2.7$ to 5.5 V
	Programming and erasure endurance	10,000 times (data flash) 1,000 times (program ROM)
Operating Ambient Temperature		-20 to 85°C
		-40 to 85°C (D version)
		-20 to 105°C (Y version) ⁽²⁾
Package		20-pin molded-plastic LSSOP
		20-pin molded-plastic SDIP
		28-pin molded-plastic HWQFN

NOTE:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Please contact Renesas Technology sales offices for the Y version.

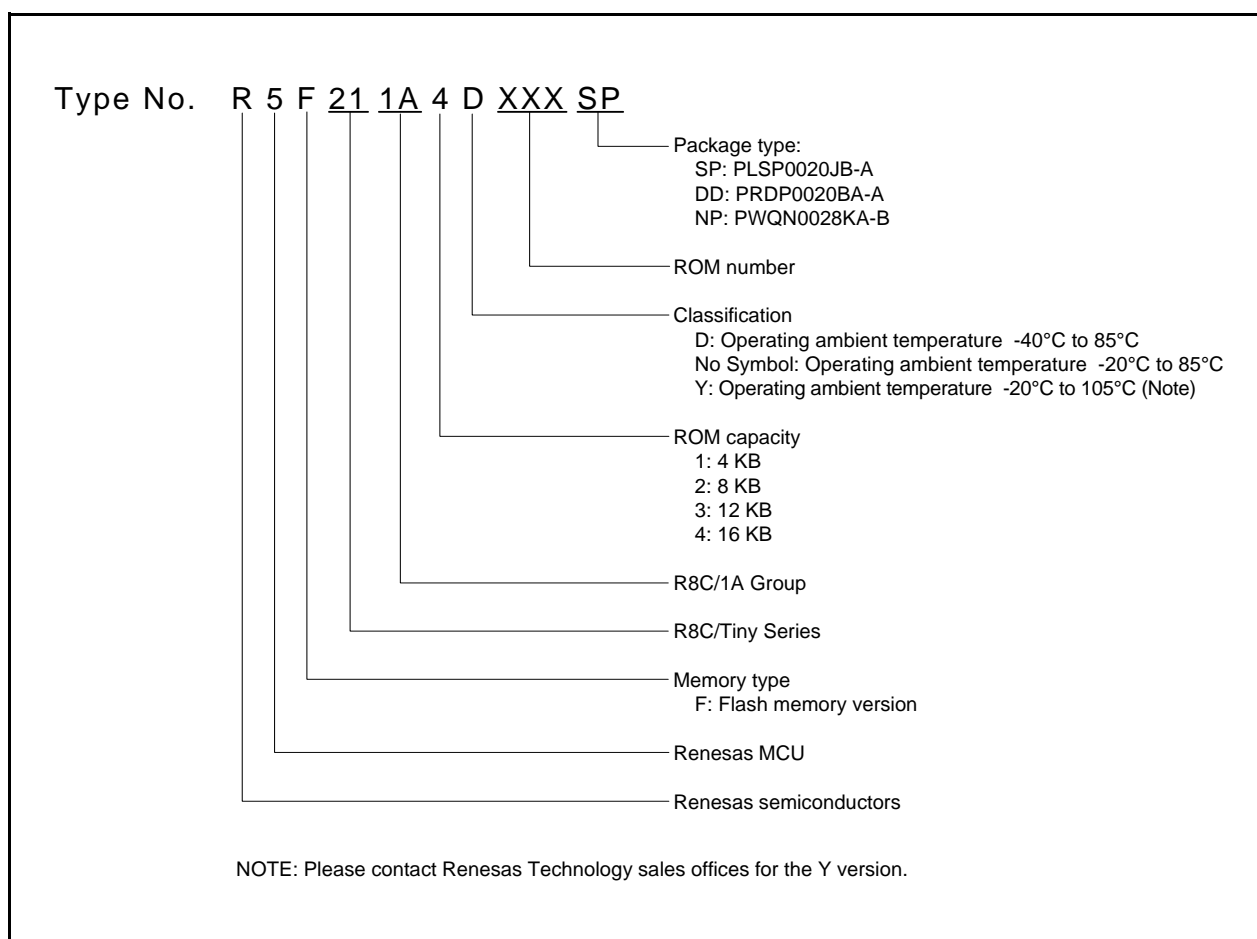


Figure 1.2 Type Number, Memory Size, and Package of R8C/1A Group

Table 1.4 Product Information for R8C/1B Group

Current of October 2006

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F211B1SP	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	D version
R5F211B2SP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F211B3SP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F211B4SP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F211B1DSP	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	
R5F211B2DSP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F211B3DSP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F211B4DSP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F211B1DD	4 Kbytes	1 Kbyte × 2	384 bytes	PRDP0020BA-A	
R5F211B2DD	8 Kbytes	1 Kbyte × 2	512 bytes	PRDP0020BA-A	
R5F211B3DD	12 Kbytes	1 Kbyte × 2	768 bytes	PRDP0020BA-A	
R5F211B4DD	16 Kbytes	1 Kbyte × 2	1 Kbyte	PRDP0020BA-A	
R5F211B2NP	8 Kbytes	1 Kbyte × 2	512 bytes	PWQN0028KA-B	
R5F211B3NP	12 Kbytes	1 Kbyte × 2	768 bytes	PWQN0028KA-B	
R5F211B4NP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PWQN0028KA-B	
R5F211B1XXXSP	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	Factory programming product ⁽¹⁾
R5F211B2XXXSP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F211B3XXXSP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F211B4XXXSP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F211B1DXXXSP	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	
R5F211B2DXXXSP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F211B3DXXXSP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F211B4DXXXSP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F211B1XXXDD	4 Kbytes	1 Kbyte × 2	384 bytes	PRDP0020BA-A	Factory programming product ⁽¹⁾
R5F211B2XXXDD	8 Kbytes	1 Kbyte × 2	512 bytes	PRDP0020BA-A	
R5F211B3XXXDD	12 Kbytes	1 Kbyte × 2	768 bytes	PRDP0020BA-A	
R5F211B4XXXDD	16 Kbytes	1 Kbyte × 2	1 Kbyte	PRDP0020BA-A	
R5F211B2XXXNP	8 Kbytes	1 Kbyte × 2	512 bytes	PWQN0028KA-B	
R5F211B3XXXNP	12 Kbytes	1 Kbyte × 2	768 bytes	PWQN0028KA-B	
R5F211B4XXXNP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PWQN0028KA-B	

NOTE:

1. The user ROM is programmed before shipment.

1.5 Pin Assignments

Figure 1.4 shows Pin Assignments for PLSP0020JB-A Package (Top View), Figure 1.5 shows Pin Assignments for PRDP0020BA-A Package (Top View) and Figure 1.6 shows Pin Assignments for PWQN0028KA-B Package (Top View).

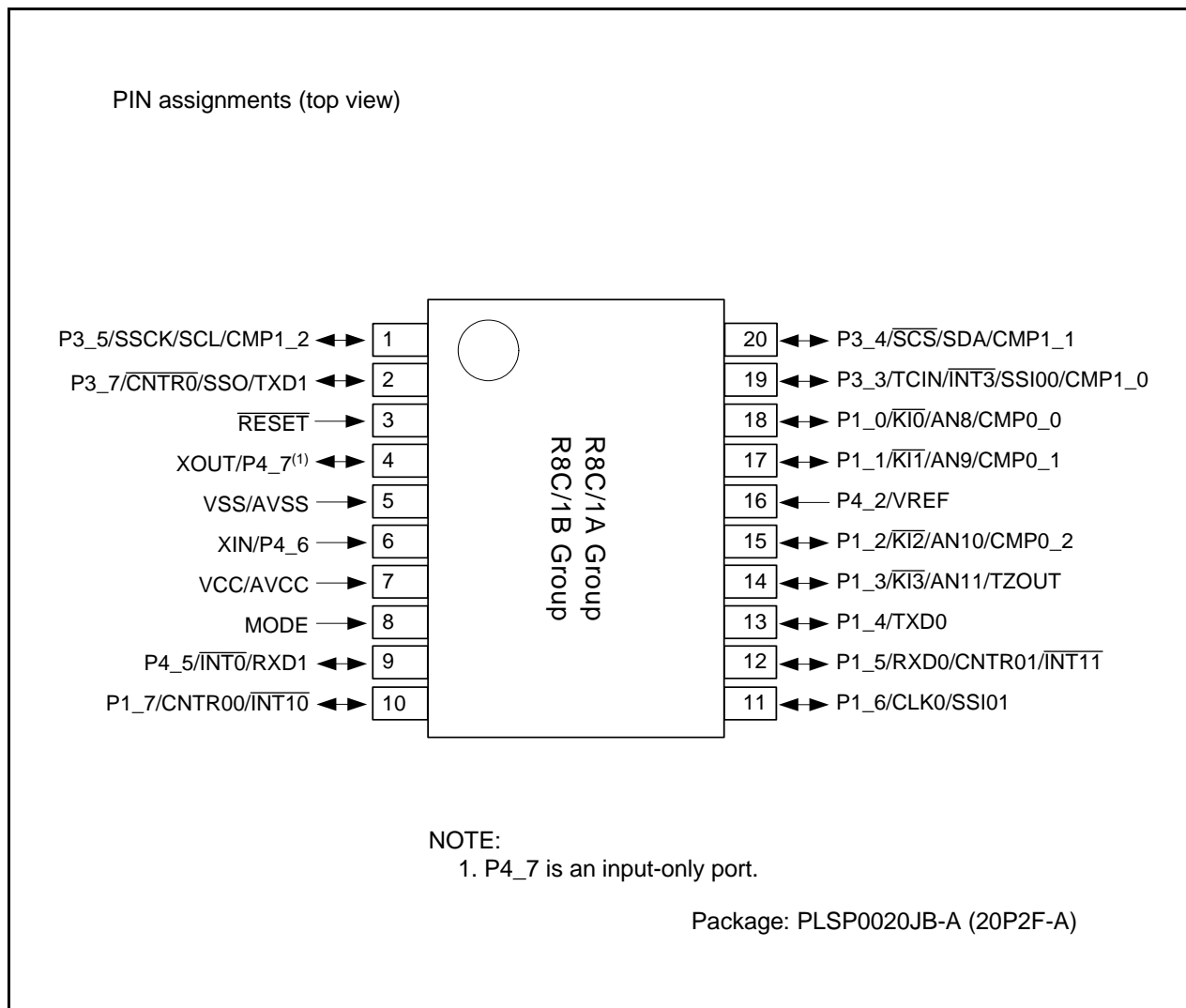


Figure 1.4 Pin Assignments for PLSP0020JB-A Package (Top View)

Table 1.7 Pin Name Information by Pin Number of PWQN0028KA-B Package

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	Clock Synchronous Serial I/O with Chip Select	I ² C bus Interface	A/D Converter
1	NC							
2	XOUT	P4_7						
3	VSS/AVSS							
4	NC							
5	NC							
6	XIN	P4_6						
7	NC							
8	VCC/AVCC							
9	MODE							
10		P4_5	$\overline{\text{INT0}}$		RXD1			
11		P1_7	$\overline{\text{INT10}}$	CNTR00				
12		P1_6			CLK0	SSI01		
13		P1_5	$\overline{\text{INT11}}$	CNTR01	RXD0			
14		P1_4			TXD0			
15	NC							
16		P1_3	$\overline{\text{KI3}}$	TZOUT				AN11
17		P1_2	$\overline{\text{KI2}}$	CMP0_2				AN10
18	NC							
19	NC							
20	VREF	P4_2						
21	NC							
22		P1_1	$\overline{\text{KI1}}$	CMP0_1				AN9
23		P1_0	$\overline{\text{KI0}}$	CMP0_0				AN8
24		P3_3	$\overline{\text{INT3}}$	TCIN/CMP1_0		SSI00		
25		P3_4		CMP1_1		$\overline{\text{SCS}}$	SDA	
26		P3_5		CMP1_2		SSCK	SCL	
27		P3_7		$\overline{\text{CNTR0}}$	TXD1	SSO		
28	$\overline{\text{RESET}}$							

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer and arithmetic and logic operations. A1 is analogous to A0. A1 can be combined with A0 and used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when the operation results in an overflow; otherwise to 0.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/1A Group

Figure 3.1 is a Memory Map of R8C/1A Group. The R8C/1A Group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 00000h. For example, a 16-Kbyte internal ROM area is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 1-Kbyte internal RAM area is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

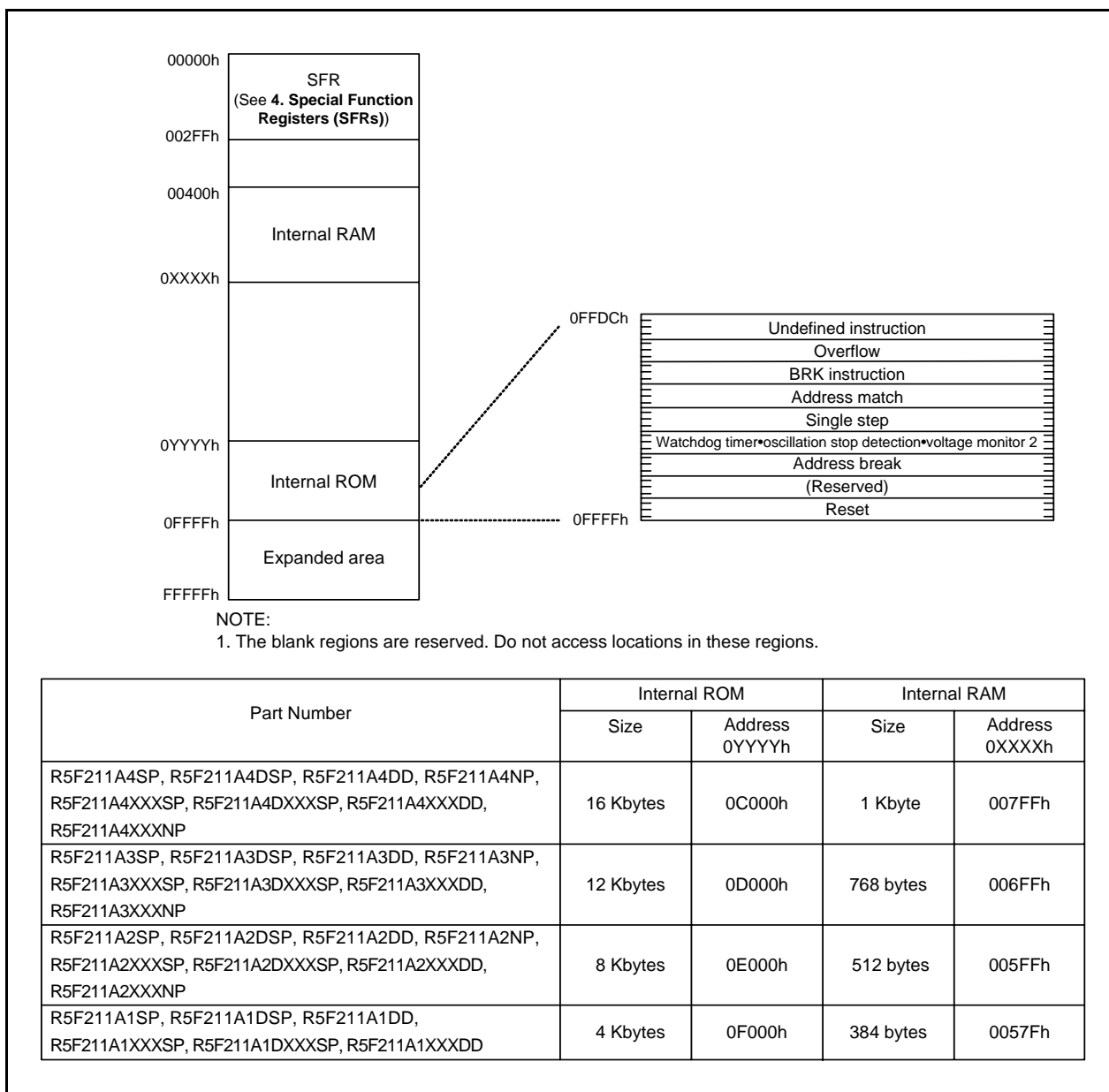


Figure 3.1 Memory Map of R8C/1A Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.4 list the special function registers.

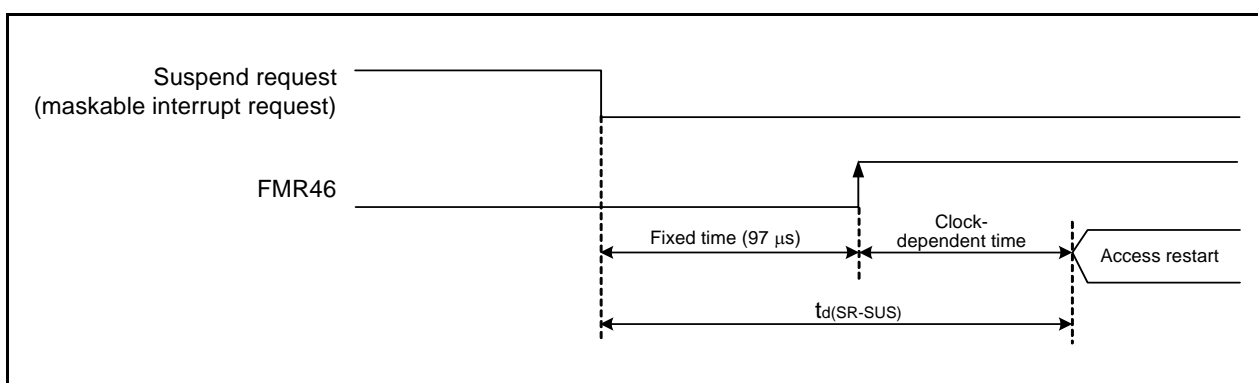
Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h	Address Match Interrupt Enable Register	AIER	00h
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OSD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h			
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			X0h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h
001Dh			
001Eh	INT0 Input Filter Select Register	INT0F	00h
001Fh			
0020h	High-Speed On-Chip Oscillator Control Register 0	HRA0	00h
0021h	High-Speed On-Chip Oscillator Control Register 1	HRA1	When shipping
0022h	High-Speed On-Chip Oscillator Control Register 2	HRA2	00h
0023h			
0024h			
0025h			
0026h			
0027h			
0028h			
0029h			
002Ah			
002Bh			
002Ch			
002Dh			
002Eh			
002Fh			
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 01000000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽²⁾	VW1C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect this register.
3. After hardware reset.
4. After power-on reset or voltage monitor 1 reset.
5. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect b2 and b3.

**Figure 5.2 Transition Time to Suspend****Table 5.6 Voltage Detection 1 Circuit Electrical Characteristics**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det1}	Voltage detection level ⁽³⁾		2.70	2.85	3.00	V
—	Voltage detection circuit self power consumption	VCA26 = 1, V _{CC} = 5.0 V	—	600	—	nA
t _{d(E-A)}	Waiting time until voltage detection circuit operation starts ⁽²⁾		—	—	100	μs
V _{ccmin}	MCU operating voltage minimum value		2.7	—	—	V

NOTES:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = -40°C to 85 °C.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.
3. Ensure that V_{det2} > V_{det1}.

Table 5.7 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det2}	Voltage detection level ⁽⁴⁾		3.00	3.30	3.60	V
—	Voltage monitor 2 interrupt request generation time ⁽²⁾		—	40	—	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, V _{CC} = 5.0 V	—	600	—	nA
t _{d(E-A)}	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

NOTES:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = -40°C to 85 °C.
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.
4. Ensure that V_{det2} > V_{det1}.

Table 5.10 High-Speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency when the reset is deasserted	$V_{CC} = 5.0\text{ V}$, $T_{opr} = 25\text{ }^{\circ}\text{C}$	—	8	—	MHz
—	High-speed on-chip oscillator frequency temperature • supply voltage dependence ⁽²⁾	0 to +60 $^{\circ}\text{C}$ /5 V \pm 5 % ⁽³⁾	7.76	—	8.24	MHz
		-20 to +85 $^{\circ}\text{C}$ /2.7 to 5.5 V ⁽³⁾	7.68	—	8.32	MHz
		-40 to +85 $^{\circ}\text{C}$ /2.7 to 5.5 V ⁽³⁾	7.44	—	8.32	MHz

NOTES:

1. The measurement condition is $V_{CC} = 5.0\text{ V}$ and $T_{opr} = 25\text{ }^{\circ}\text{C}$.
2. Refer to **10.6.4 High-Speed On-Chip Oscillator Clock** for notes on high-speed on-chip oscillator clock.
3. The standard value shows when the HRA1 register is assumed as the value in shipping and the HRA2 register value is set to 00h.

Table 5.11 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on ⁽²⁾		1	—	2000	μs
$t_{d(R-S)}$	STOP exit time ⁽³⁾		—	—	150	μs

NOTES:

1. The measurement condition is $V_{CC} = 2.7\text{ to }5.5\text{ V}$ and $T_{opr} = 25\text{ }^{\circ}\text{C}$.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts after the interrupt is acknowledged to exit stop mode.

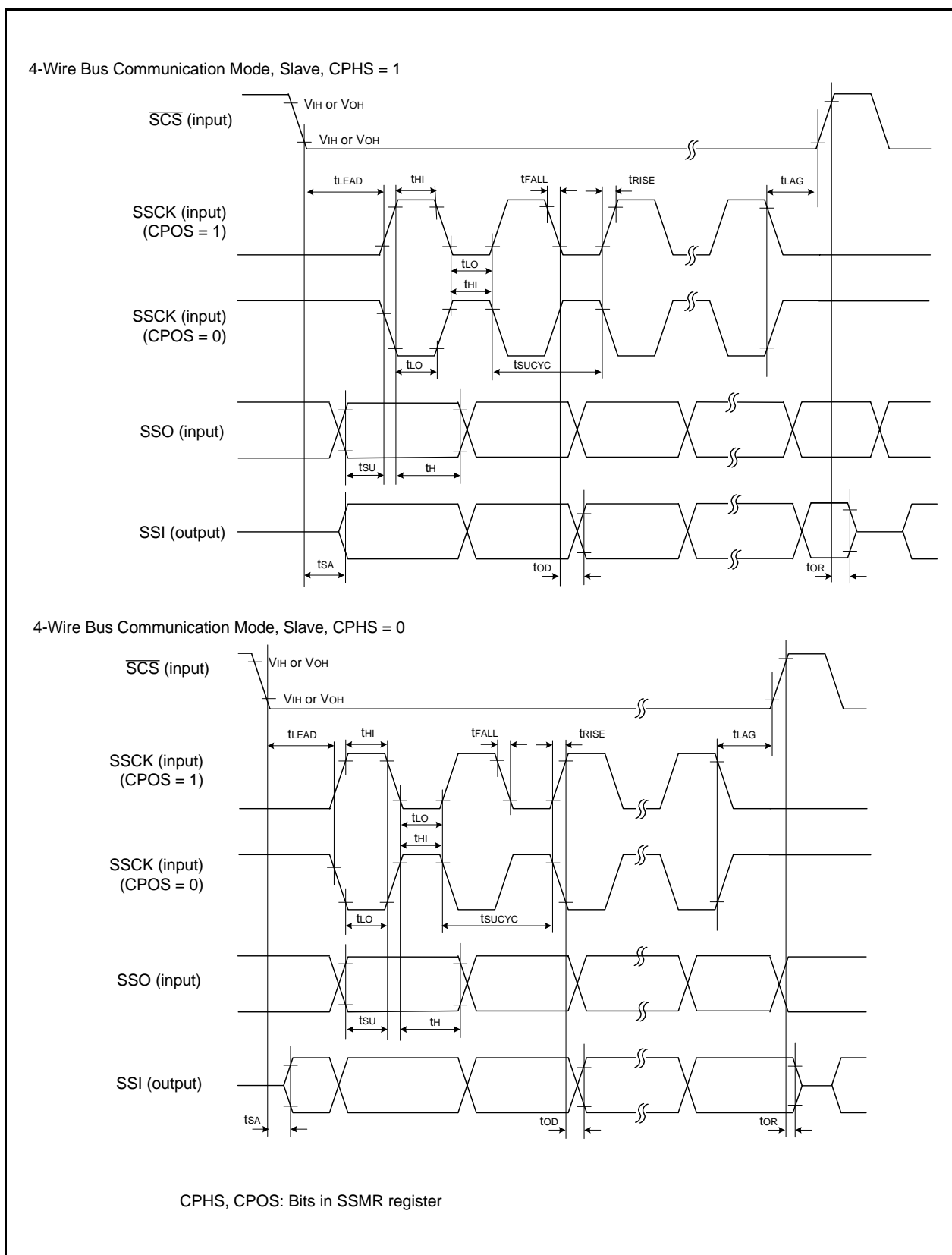


Figure 5.5 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

Table 5.13 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{CYC} +600 ⁽²⁾	—	—	ns
t _{SCLH}	SCL input "H" width		3t _{CYC} +300 ⁽²⁾	—	—	ns
t _{SCLL}	SCL input "L" width		5t _{CYC} +300 ⁽²⁾	—	—	ns
t _{sf}	SCL, SDA input fall time		—	—	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		—	—	1t _{CYC} ⁽²⁾	ns
t _{BUF}	SDA input bus-free time		5t _{CYC} ⁽²⁾	—	—	ns
t _{STAH}	Start condition input hold time		3t _{CYC} ⁽²⁾	—	—	ns
t _{STAS}	Retransmit start condition input setup time		3t _{CYC} ⁽²⁾	—	—	ns
t _{STOS}	Stop condition input setup time		3t _{CYC} ⁽²⁾	—	—	ns
t _{SDAS}	Data input setup time		1t _{CYC} +20 ⁽²⁾	—	—	ns
t _{SDAH}	Data input hold time		0	—	—	ns

NOTES:

1. V_{CC} = 2.7 to 5.5 V, V_{SS} = 0 V and T_a = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. 1t_{CYC} = 1/f₁(s)

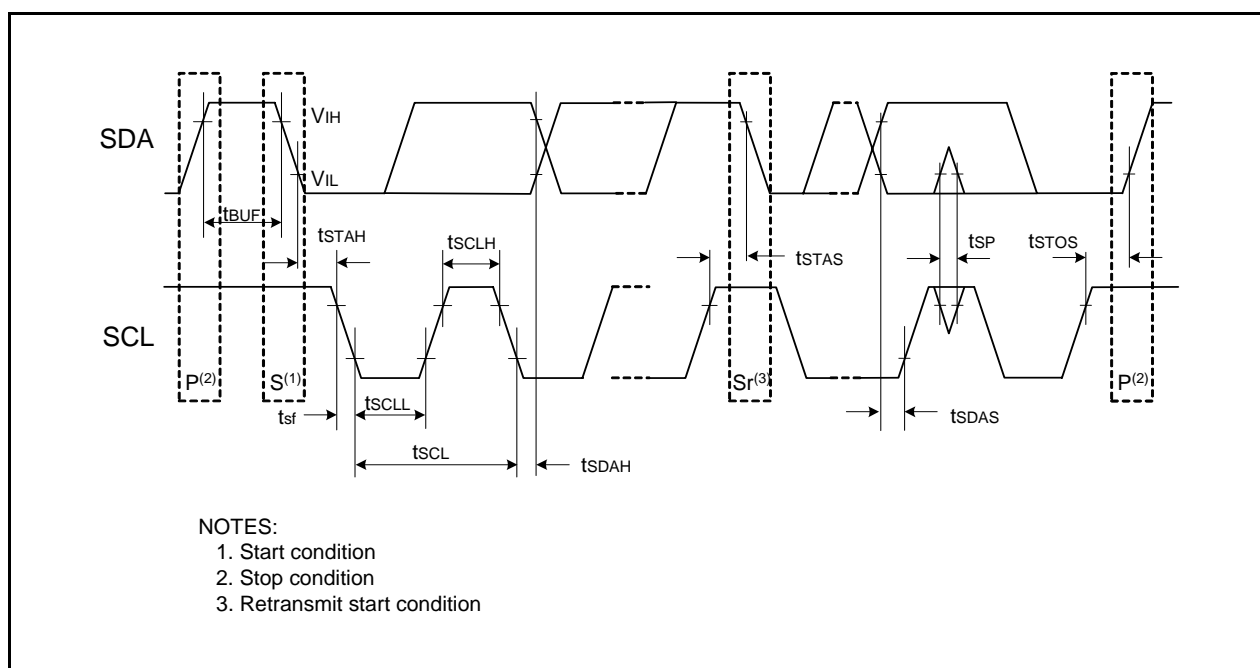
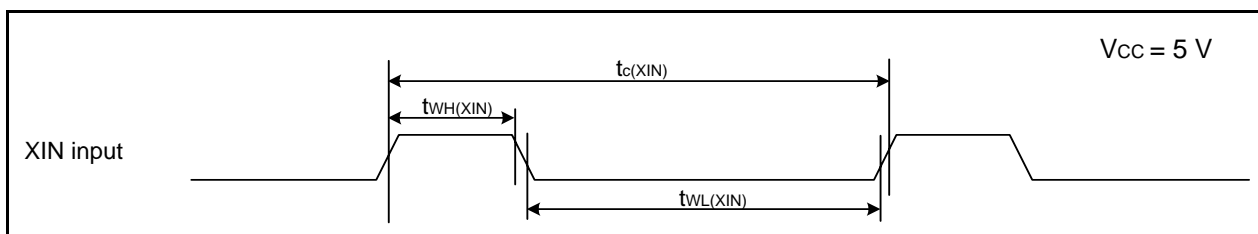
**Figure 5.7 I/O Timing of I²C bus Interface**

Table 5.15 Electrical Characteristics (2) [Vcc = 5 V] (Topr = -40 to 85 °C, unless otherwise specified.)

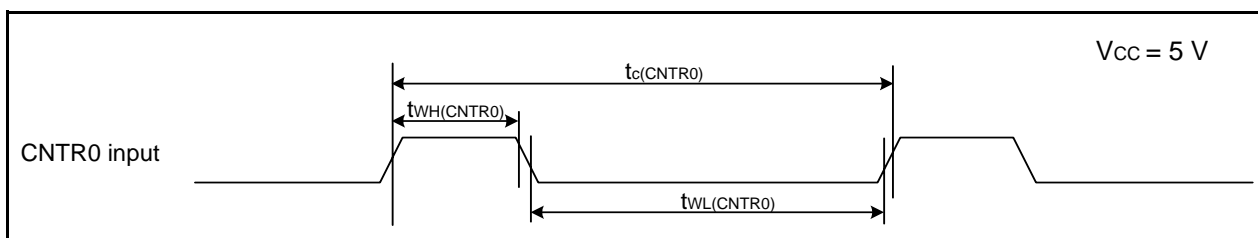
Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss, A/D converter is stopped	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8	14	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5	–	mA
		Medium-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2	–	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	4	8	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	110	300	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	–	40	80	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0	–	38	76	μA
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	–	0.8	3.0	μA

Timing Requirements**(Unless otherwise specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_a = 25\text{ }^{\circ}\text{C}$) [$V_{CC} = 5\text{ V}$]****Table 5.16 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	50	–	ns
$t_{WH(XIN)}$	XIN input "H" width	25	–	ns
$t_{WL(XIN)}$	XIN input "L" width	25	–	ns

**Figure 5.8 XIN Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.17 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CNTR0)}$	CNTR0 input cycle time	100	–	ns
$t_{WH(CNTR0)}$	CNTR0 input "H" width	40	–	ns
$t_{WL(CNTR0)}$	CNTR0 input "L" width	40	–	ns

**Figure 5.9 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.18 TCIN Input, $\overline{INT3}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TCIN)}$	TCIN input cycle time	400 ⁽¹⁾	–	ns
$t_{WH(TCIN)}$	TCIN input "H" width	200 ⁽²⁾	–	ns
$t_{WL(TCIN)}$	TCIN input "L" width	200 ⁽²⁾	–	ns

NOTES:

1. When using timer C input capture mode, adjust the cycle time to (1/timer C count source frequency x 3) or above.
2. When using timer C input capture mode, adjust the pulse width to (1/timer C count source frequency x 1.5) or above.

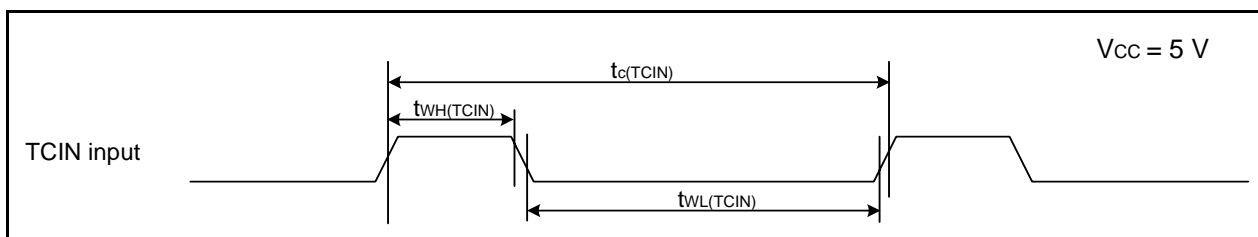
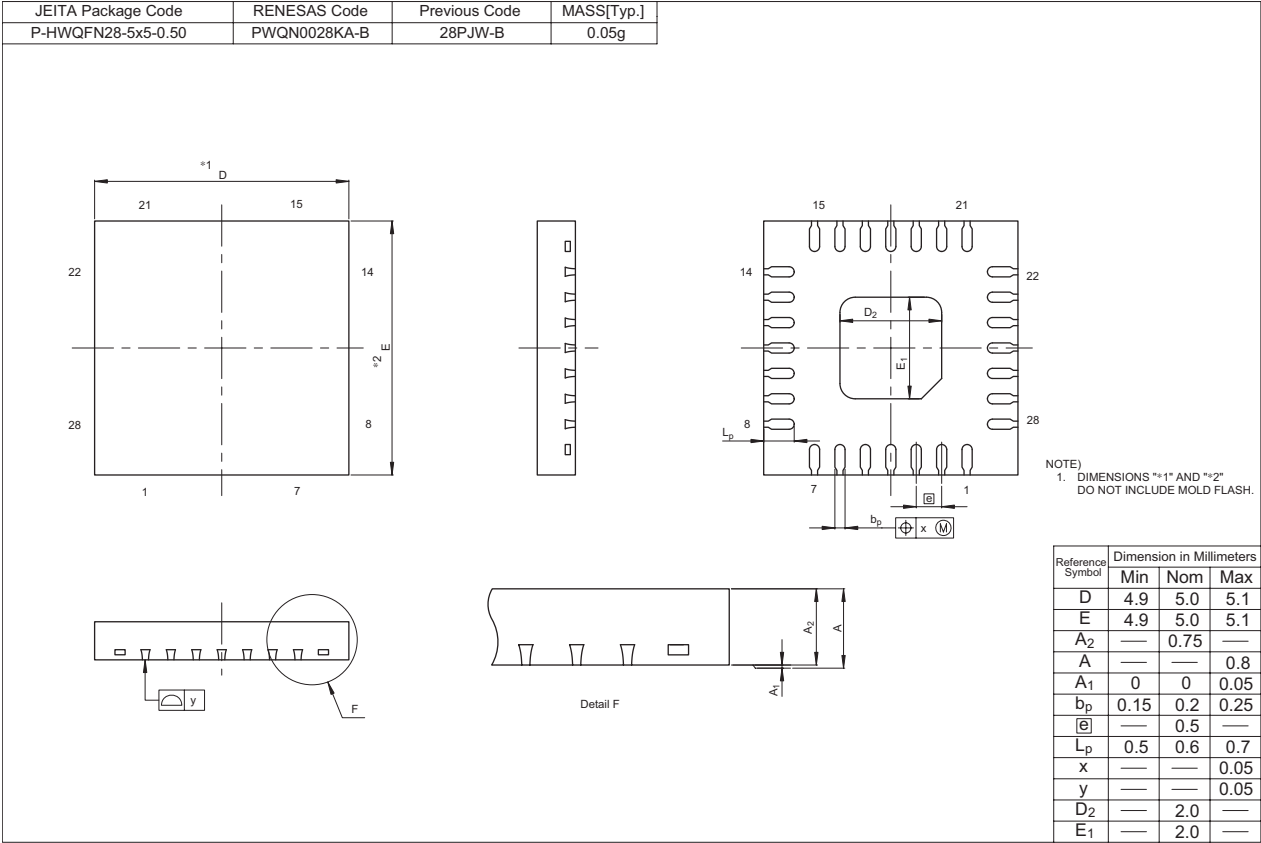
**Figure 5.10 TCIN Input, $\overline{INT3}$ Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.21 Electrical Characteristics (3) [V_{CC} = 3V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except X _{OUT}	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		X _{OUT}	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P1_0 to P1_3, X _{OUT}	I _{OL} = 1 mA		—	—	0.5	V
		P1_0 to P1_3	Drive capacity HIGH	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	—	—	0.5	V
		X _{OUT}	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT3, KI0, KI1, KI2, KI3, CNTR0, CNTR1, TCIN, RXD0			0.2	—	0.8	V
		RESET			0.2	—	1.8	V
I _{IH}	Input "H" current		V _I = 3 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		66	160	500	kΩ
R _{IXIN}	Feedback resistance	XIN			—	3.0	—	MΩ
f _{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V _{RAM}	RAM hold voltage		During stop mode		2.0	—	—	V

NOTE:

1. V_{CC} = 2.7 to 3.3 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN) = 10 MHz, unless otherwise specified.



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Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
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